

ABSTRACT

When mounting an IC chip ~~1~~ on a circuit board ~~4~~,
bumps ~~3~~ are formed on electrodes ~~2~~^{of} on the IC chip, and the
5 bumps and the electrodes of the circuit board are aligned in
position with each other with interposition of an insulative
thermosetting resin ~~8~~ having no conductive particle between
the electrodes of the circuit board and the bumps. The IC
chip is pressed against the circuit board with a pressure
10 force of not smaller than 20 gf per bump by a heated head ~~8~~
so as to perform warp correction of the IC chip and the
board, while the resin interposed between the IC chip and
the circuit board is hardened to bond the IC chip and the
circuit board together.